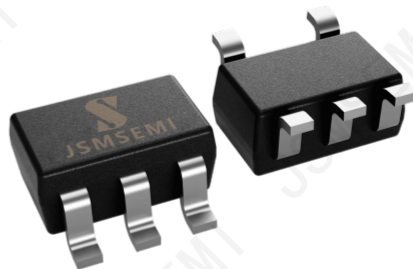


Description

This single inverter gate is designed for 1.65V to 5.5V VCC operation. The MC74HC1G04 device performs the Boolean function $Y = \overline{A}$.

The CMOS device has high output drive while maintaining low static power dissipation over a broad VCC operating range.

The MC74HC1G04 device is available in Green SOT23-5 and SOT-353 packages. It operates over an ambient temperature range of -40°C to +125°C.



Simplified Schematic

Features

- Packages: SOT23-5, SOT-353(SC70-5)
- Supports 5V V_{CC} operation
- Inputs accept voltages up to 5.5V allowing down translation to V_{CC}
- Typ t_{pd} of 4.2ns at 3.3V
- Low power consumption, 1 μ A maximum I_{CC}
- ± 24 mA output drive at 3V
- I_{off} supports live-insertion, partial-power-down mode, and back-drive protection
- ESD protection exceeds JESD 22
 - 2000V human-body model
 - 200V machine model
 - 1000V charged-device model
- Operating Temperature Range: -40°C to +125°C
- RoSH compatible

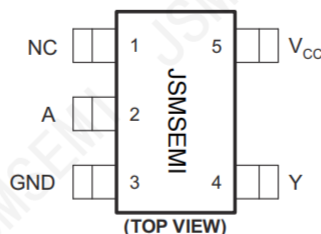
Applications

- AV receiver
- Audio dock: portable
- Blu-ray player and home theater
- Embedded PC
- MP3 player/recorder (portable audio)
- Personal Digital Assistant (PDA)
- Power: telecom/server AC/DC supply: single controller: analog and digital
- Solid State Drive (SSD): client and enterprise
- TV: LCD/digital and high-definition (HDTV)
- Tablet: enterprise
- Video analytics: server
- Wireless headset, keyboard, and mouse

Ordering Information

Order number	Package	Marking	Operation Temperature Range	MSL Grade	Ship,Quantity	Green
MC74HC1G04DTT1G-JSM	SOT-23-5L	C04F	-40 to 125°C	3	TR&3000	Rohs
MC74HC1G04DFT1G-JSM	SOT-353	CCF	-40 to 125°C	3	TR&3000	Rohs

Pin Configuration and Functions



Pin Functions

PIN		DESCRIPTION
NAME	SOT23-5 SOT-353	
NC	1	No connect
A	2	Input
GND	3	Ground
Y	4	Output
V _{CC}	5	Power terminal

Specifications

Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	-0.5	6.5	V
V _I	Input voltage range	-0.5	6.5	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	6.5	V
V _O	Voltage range applied to any output in the high or low state ^{(2) (3)}	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current		-50	mA
I _{OK}	Output clamp current		-50	mA
I _O	Continuous output current		±50	mA
	Continuous current through V _{CC} or GND		±100	mA
T _{stg}	Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the Recommended Operating Conditions table.

ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM)	±2000
		Charged device model (CDM)	±1000

Recommended Operating Conditions

(1)			MIN	MAX	UNIT
V _{CC}	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V _{IH}	High-level input voltage	V _{CC} = 1.65V to 1.95V	0.65 × V _{CC}		V
		V _{CC} = 2.3V to 2.7V	1.7		
		V _{CC} = 3V to 3.6V	2		
		V _{CC} = 4.5V to 5.5V	0.7 × V _{CC}		
V _{IL}	Low-level input voltage	V _{CC} = 1.65V to 1.95V		0.35 × V _{CC}	V
		V _{CC} = 2.3V to 2.7V		0.7	
		V _{CC} = 3V to 3.6V		0.8	
		V _{CC} = 4.5V to 5.5V		0.3 × V _{CC}	
V _I	Input voltage		0	5.5	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65V		−4	mA
		V _{CC} = 2.3V		−8	
		V _{CC} = 3V		−16	
		V _{CC} = 4.5V		−24	
I _{OL}	Low-level output current	V _{CC} = 1.65V		4	mA
		V _{CC} = 2.3V		8	
		V _{CC} = 3V		16	
		V _{CC} = 4.5V		24	
Δt/Δv	Input transition rise or fall rate	V _{CC} = 1.8V ± 0.15V, 2.5V ± 0.2V		20	ns/V
		V _{CC} = 3.3V ± 0.3V		10	
		V _{CC} = 5V ± 0.5V		5	
T _A	Operating free-air temperature		−40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

Thermal Information

THERMAL METRIC		MC74HC1G04		UNIT
		SOT23	SC70	
		5 PINS	5 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	357.1	371.0	°C/W
R _{θJctop}	Junction-to-case (top) thermal resistance	263.7	297.5	
R _{θJB}	Junction-to-board thermal resistance	264.4	258.6	
ψ _{JT}	Junction-to-top characterization parameter	195.6	195.6	
ψ _{JB}	Junction-to-board characterization parameter	262.2	256.2	
R _{θJcbot}	Junction-to-case (bottom) thermal resistance	—	—	

Electrical Characteristics—DC Limit Changes

over recommended operating free-air temperature range (Full=-40°C to +125°C, typical values are at T_A = +25°C, unless otherwise noted.) ⁽¹⁾

PARAMETER		TEST CONDITIONS	V _{CC}	TEMP	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
V _{OH}		I _{OH} = -100μA	1.65V to 5.5V	Full	V _{CC} -0.1			V
		I _{OH} = -4mA	1.65V		1.2			
		I _{OH} = -8mA	2.3V		1.9			
		I _{OH} = -16mA	3V		2.4			
		I _{OH} =- 24mA			2.3			
		I _{OH} = -32mA	4.5V		3.8			
V _{OL}		I _{OL} = 100μA	1.65V to 5.5V	Full			0.1	V
		I _{OL} = 4mA	1.65V				0.45	
		I _{OL} = 8mA	2.3V				0.3	
		I _{OL} = 16mA	3V				0.4	
		I _{OL} = 24mA					0.55	
		I _{OL} = 32mA	4.5V				0.55	
I _I	A input	V _I =5.5V or GND	0V to 5.5V	+25°C		±0.1	±1	μA
				Full			±5	
I _{off}		V _I or V _O =5.5V	0	+25°C		±0.1	±1	μA
				Full			±10	
I _{CC}		V _I =5.5V or GND, I _O =0	1.65V to 5.5V	+25°C		0.1	1	μA
				Full			10	
ΔI _{CC}		One input at V _{CC} -0.6V, Other inputs at V _{CC} or GND	3V to 5.5V	Full			500	μA
Input Capacitance (C _i)		V _I =V _{CC} or GND	3.3V	+25°C		4		pF

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

(2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

Electrical Characteristics—AC Limit Changes

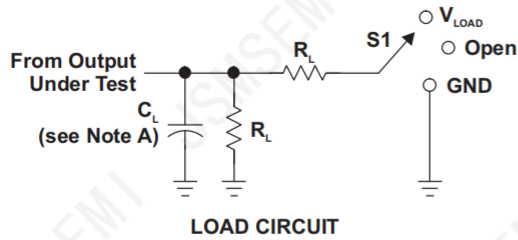
PARAMETER	SYMBOL	TEST CONDITIONS		MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
Propagation Delay	t _{pd}	V _{CC} =1.8V±0.15V	C _L =30pF, R _L =1KΩ		13.0		ns
		V _{CC} =2.5V±0.2V	C _L =30pF, R _L =500Ω		5.1		
		V _{CC} =3.3V±0.3V	C _L =50pF, R _L =500Ω		4.2		
		V _{CC} =5V±0.5V	C _L =50pF, R _L =500Ω		3.3		
Power dissipation capacitance	C _{pd}	V _{CC} =1.8V	f=10MHz		16		pF
		V _{CC} =2.5V			18		
		V _{CC} =3.3V			18		
		V _{CC} =5V			20		

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

(2) This parameter is ensured by design and/or characterization and is not tested in production.

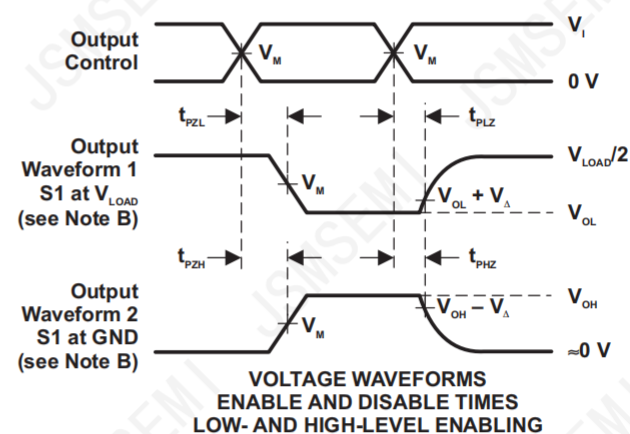
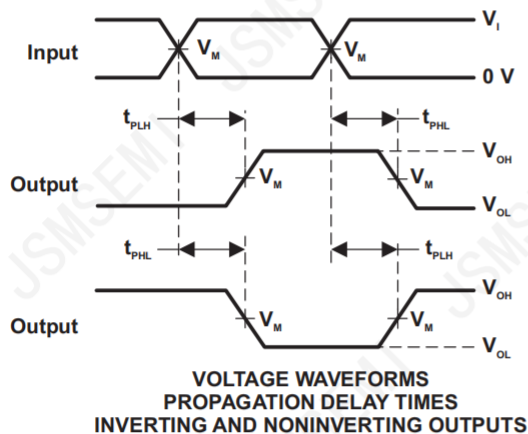
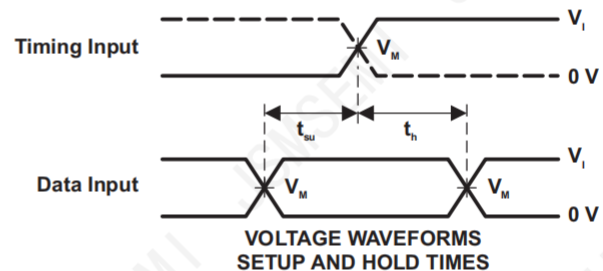
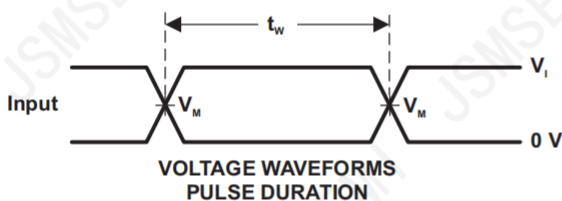
(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

Parameter Measurement Information



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

V_{CC}	INPUTS		V_M	V_{LOAD}	C_L		R_L		V_{Δ}
	V_I	t_r/t_f							
$1.8V \pm 0.15V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	15pF	30pF	1M Ω	1k Ω	0.15V
$2.5V \pm 0.2V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	15pF	30pF	1M Ω	500 Ω	0.15V
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	6V	15pF	50pF	1M Ω	500 Ω	0.3V
$5V \pm 0.5V$	V_{CC}	$\leq 2.5ns$	$V_{CC}/2$	$2 \times V_{CC}$	15pF	50pF	1M Ω	500 Ω	0.3V



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_o = 50 \Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{SU} .
 - t_{PZL} and t_{PZH} are the same as t_{H} .
 - t_{PLH} and t_{PHL} are the same as t_{PD} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

Detailed Description

Overview

The MC74HC1G04 device contains inverter gate and performs the Boolean function $Y = \bar{A}$. This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

Functional Block Diagram



Feature Description

- Wide operating voltage range.
 - Operates from 1.65V to 5.5V.
- Allows down voltage translation.
- Inputs accept voltages to 5.5V.
- I_{off} feature allows voltages on the inputs and outputs, when V_{CC} is 0V.

Device Functional Modes

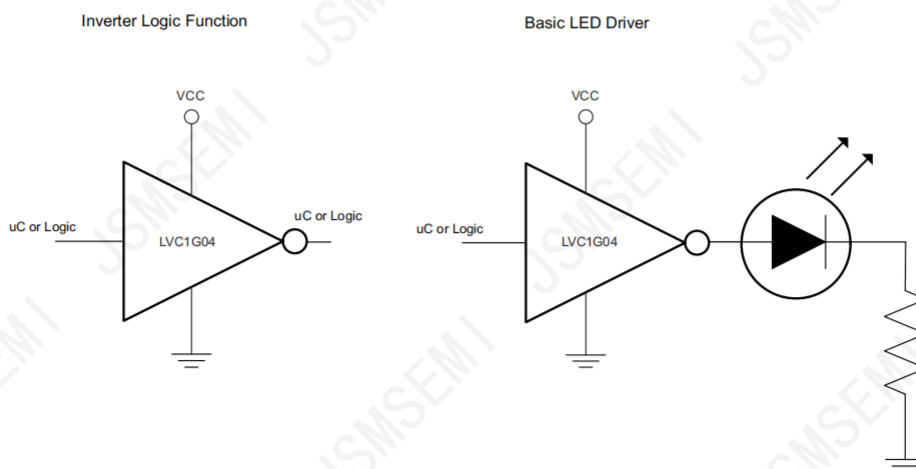
Function Table

INPUT	OUTPUT
A	Y
H	L
L	H

Application Information

The MC74HC1G04 is a high drive CMOS device that can be used for implementing inversion logic with a high output drive, such as an LED application. It can produce 24mA of drive current at 3.3V making it ideal for driving multiple outputs and good for high speed applications up to 100Mhz. The inputs are 5.5V tolerant allowing it to translate down to V_{CC} .

Typical Application



Power Supply Recommendations

The power supply can be any voltage between the min and max supply voltage rating located in the Recommended Operating Conditions table.

Each VCC pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1 μ F capacitor is recommended. If there are multiple VCC pins, then a 0.01 μ F or 0.022 μ F capacitor is recommended for each power pin. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. 0.1 μ F and 1 μ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

Layout

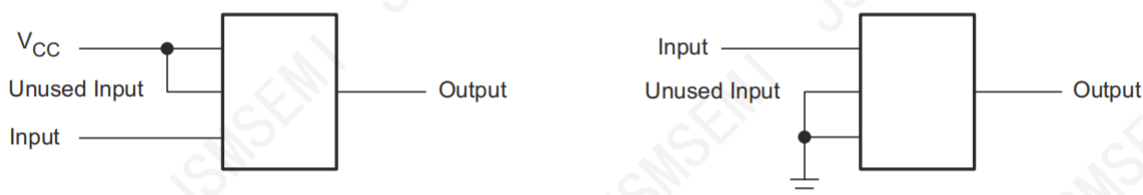
Layout Guidelines

When using multiple bit logic devices, inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. The rules that must be observed under all circumstances are specified in the next paragraph.

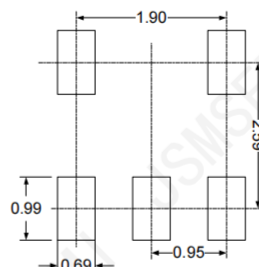
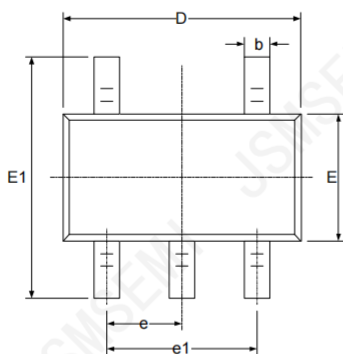
All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or VCC; whichever makes more sense or is more convenient.

Layout Example

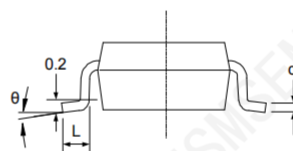
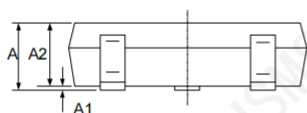


Package Information

SOT-23-5L



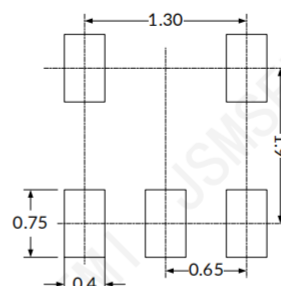
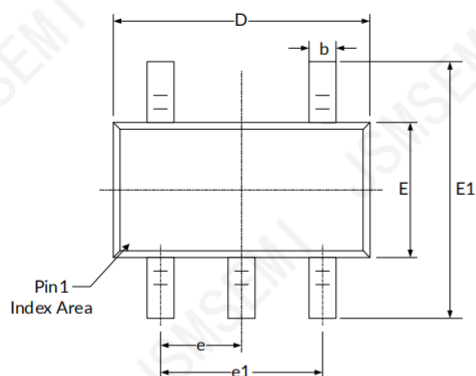
RECOMMENDED LAND PATTERN (Unit: mm)



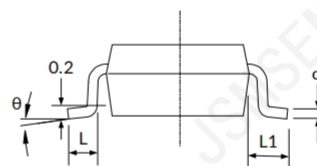
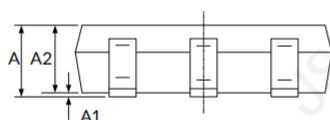
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Package Information

SOT-353(SC70-5)



RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.080	0.150	0.003	0.006
D ⁽¹⁾	2.000	2.200	0.079	0.087
E ⁽¹⁾	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650(BSC)		0.026(BSC)	
e1	1.300(BSC)		0.051(BSC)	
L	0.260	0.460	0.010	0.018
L1	0.525		0.021	
θ	0°	8°	0°	8°

Revision History

Rev.	Change	Date
V1.0	Initial version	6/27/2021

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